

## Software License Agreement For SafeTI Hercules Diagnostic Library CSP (Production)

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12. **PRC Provisions.** If you are located in the People’s Republic of China (“**PRC**”) or if the Licensed Materials will be sent to the PRC, the following provisions shall apply:
- a. **Registration Requirements.** You shall be solely responsible for performing all acts and obtaining all approvals that may be required in connection with this Agreement by the government of the PRC, including but not limited to registering pursuant to, and otherwise complying with, the PRC Measures on the Administration of Software Products, Management Regulations on Technology Import-Export, and Technology Import and Export Contract Registration Management Rules. Upon receipt of such approvals from the government authorities, you shall forward evidence of all such approvals to TI for its records. In the event that you fail to obtain any such approval or registration, you shall be solely responsible for any and all losses, damages or costs resulting therefrom, and shall indemnify TI for all such losses, damages or costs.
  - b. **Governing Language.** This Agreement is written and executed in the English language and shall be authoritative and controlling, whether or not translated into a language other than English to comply with law or for reference purposes. If a translation of this Agreement is required for any purpose, including but not limited to registration of the Agreement pursuant to any governmental laws, regulations or rules, you shall be solely responsible for creating such translation.
13. **Contingencies.** TI shall not be in breach of this Agreement and shall not be liable for any non-performance or delay in performance if such non-performance or delay is due to a force majeure event or other circumstances beyond TI’s reasonable control.
14. **Entire Agreement.** This is the entire agreement between you and TI and this Agreement supersedes any prior agreement between the parties related to the subject matter of this Agreement. Notwithstanding the foregoing, any signed and effective software license agreement relating to the subject matter hereof and stating expressly that such agreement shall control regardless of any subsequent click-wrap, shrink-wrap or web-wrap, shall supersede the terms of this Agreement. No amendment or modification of this Agreement will be effective unless in writing and signed by a duly authorized representative of TI. You hereby warrant and represent that you have obtained all authorizations and other applicable consents required empowering you to enter into this Agreement.

**Exhibit 1**  
**Licensed Materials and TI Devices**

1. TI device(s):  
This license is limited for use with TI Hercules TMS570 and RM products.
2. Licensed Materials

<b>Licensed Software for use with TI Devices only</b>	<b>Format</b>	<b>ECCN</b>
SafeTI Hercules Diagnostic Library and TPS65381 Driver	Source Code	EAR99
SafeTI Diagnostic Library Test Automation Unit	Executable Tool	EAR99
	Test Scripts Source	EAR99
	Test case xls	EAR99
LDRAunit-TI-Qual_C_CPP	Executable Tool	EAR99

<b>Compliance Support Package Documentation</b>	
<b>Title</b>	<b>Description</b>
<b>Requirements and Design</b>	
Software Safety Requirements specification	This document contains software safety requirements specification for the SafeTI Hercules Diagnostic Library.
Software Architecture Document	This document describes the software architecture of the SafeTI Hercules Diagnostic Library.
Design Document	This document describes the software design of the SafeTI Hercules Diagnostic Library.
<b>Test Documents</b>	
Detailed Static Analysis Report	This report provides summary of the Software quality metrics and the MISRA-C 2004 violations.
Detailed Dynamic Analysis Report	This report provides summary of the Structural Coverage metrics (Statement, Branch, MC/DC Coverage metrics).
Test Results Report	This report provides detailed information about the results of the formal testing.
Traceability Matrix Report	This report provides the traceability matrix between different phases of software development.